

SNx4HC594 8-Bit Shift Registers With Output Registers

1 Features

- Wide Operating Voltage Range of 2 V to 6 V
- High-Current Outputs Can Drive up to 15 LSTTL Loads
- Low Power Consumption, 80- μ A Maximum I_{CC}
- Typical $t_{pd} = 15$ ns
- ± 6 -mA Output Drive at 5 V
- Low Input Current of 1 μ A Maximum
- 8-Bit Serial-In, Parallel-Out Shift Registers With Storage
- Independent Direct Overriding Clears on Shift and Storage Registers
- Independent Clocks for Both Shift and Storage Registers

2 Applications

- Pro Audio Mixer
- Elevators and Escalators
- Human Machine Interface (HMI): Industrial Monitor
- Entertainment Systems
- Grid Infrastructure: Grid Control
- Access Control and Security: DVR and DVS

3 Description

The SNx4HC594 devices contain an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. Separate clocks and direct overriding clear (\overline{RCLR} , \overline{SRCLR}) inputs are provided on both the shift and storage registers. A serial (Q_H) output is provided for cascading purposes.

Both the shift register (SRCLK) and storage register (RCLK) clocks are positive edge triggered. If both clocks are connected together, the shift register always is one count pulse ahead of the storage register.

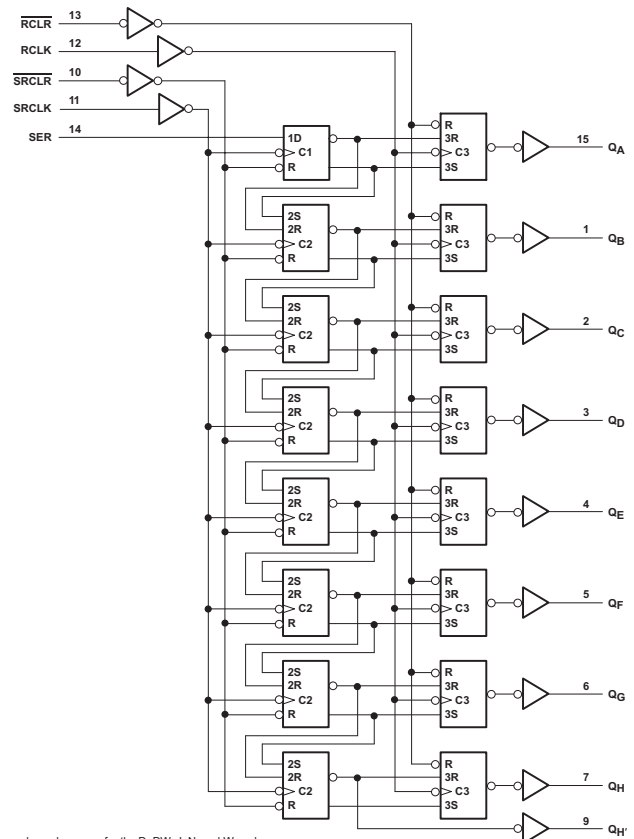
The parallel ($Q_A - Q_H$) outputs have high-current capability. Q_H is a standard output.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE (NOM)
SN74HC594	PDIP (16)	19.30 mm x 6.35 mm
	SOIC (16)	9.00 mm x 9.00 mm
		10.30 mm x 7.50 mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.

Logic Diagram (Positive Logic)



Pin numbers shown are for the D, DW, J, N, and W packages.



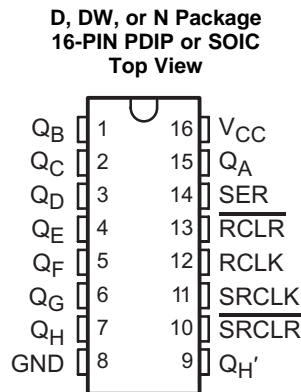
Table of Contents

1 Features 1 2 Applications 1 3 Description 1 4 Revision History 2 5 Pin Configuration and Functions 3 6 Specifications 4 6.1 Absolute Maximum Ratings 4 6.2 ESD Ratings 4 6.3 Recommended Operating Conditions 4 6.4 Thermal Information 5 6.5 Electrical Characteristics 5 6.6 Switching Characteristics: $C_L = 50$ pF 6 6.7 Switching Characteristics: $C_L = 150$ pF 6 6.8 Timing Requirements 7 6.9 Operating Characteristics 7 6.10 Typical Characteristics 9 7 Parameter Measurement Information 10 8 Detailed Description 11	8.1 Overview 11 8.2 Functional Block Diagram 11 8.3 Feature Description 11 8.4 Device Functional Modes 12 9 Application and Implementation 13 9.1 Application Information 13 9.2 Typical Application 13 10 Power Supply Recommendations 15 11 Layout 15 11.1 Layout Guidelines 15 11.2 Layout Example 15 12 Device and Documentation Support 16 12.1 Documentation Support 16 12.2 Trademarks 16 12.3 Electrostatic Discharge Caution 16 12.4 Glossary 16 13 Mechanical, Packaging, and Orderable Information 16
--	---

4 Revision History

Changes from Revision F (October 2003) to Revision G	Page
<ul style="list-style-type: none"> • Added <i>Pin Configuration and Functions</i> section, <i>ESD Ratings</i> table, <i>Feature Description</i> section, <i>Device Functional Modes</i>, <i>Application and Implementation</i> section, <i>Power Supply Recommendations</i> section, <i>Layout</i> section, <i>Device and Documentation Support</i> section, and <i>Mechanical, Packaging, and Orderable Information</i> section 1 • Removed ordering information. 1 • ESD warning added 1 	

5 Pin Configuration and Functions



Pin Functions

PIN		I/O	DESCRIPTION
NO.	NAME		
1	Q _B	O	Output B
2	Q _C	O	Output C
3	Q _D	O	Output D
4	Q _E	O	Output E
5	Q _F	O	Output F
6	Q _G	O	Output G
7	Q _H	O	Output H
8	GND	–	Ground
9	Q _H '	O	Q _H inverted
10	$\overline{\text{SRCLR}}$	I	Serial clear
11	SRCLK	I	Serial clock
12	RCLK	I	Storage clock
13	$\overline{\text{RCLR}}$	I	Storage clear
14	SER	I	Serial input
15	Q _A	O	Output A
16	V _{CC}	–	Power pin

6 Specifications

6.1 Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT	
V_{CC}	Supply voltage	-0.5	7	V	
I_{IK}	Input clamp current ⁽²⁾	$V_I < 0$ or $V_I > V_{CC}$	-20	20	mA
I_{OK}	Output clamp current ⁽²⁾	$V_O < 0$ or $V_O > V_{CC}$	-20	20	mA
I_O	Continuous output current	$V_O = 0$ to V_{CC}	-35	35	mA
Continuous current through V_{CC} or GND			-70	70	mA
θ_{JA}	Package thermal impedance ⁽³⁾	D package		73	°C/W
		DW package		57	
		N package		67	
T_{stg}	Storage temperature		-60	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

(2) The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

(3) The package thermal impedance is calculated in accordance with JESD 51-7.

6.2 ESD Ratings

		VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±2000
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1000

(1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

 over operating free-air temperature range (unless otherwise noted)⁽¹⁾

		SN54HC594 ⁽²⁾			SN74HC594			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	2	5	6	2	5	6	V
V_{IH}	High-level input voltage	$V_{CC} = 2$ V	1.5		1.5			V
		$V_{CC} = 4.5$ V	3.15		3.15			
		$V_{CC} = 6$ V	4.2		4.2			
V_{IL}	Low-level input voltage	$V_{CC} = 2$ V	0.5		0.5			V
		$V_{CC} = 4.5$ V	1.35		1.35			
		$V_{CC} = 6$ V	1.8		1.8			
V_I	Input voltage	0	V_{CC}		0	V_{CC}		V
V_O	Output voltage	0	V_{CC}		0	V_{CC}		V
t_t	Input transition (rise and fall) rate	$V_{CC} = 2$ V	1000		1000			ns
		$V_{CC} = 4.5$ V	500		500			
		$V_{CC} = 6$ V	400		400			
T_A	Operating free-air temperature	-55	125		-40	125		°C

(1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, [SCBA004](#).

(2) Product Preview

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		SN74HC594			UNIT
		N (PDIP)	D (SOIC)	DW (SOIC)	
		16 PINS	16 PINS	16 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	41.3	72.3	71	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	28	33.2	32.3	
R _{θJB}	Junction-to-board thermal resistance	21.3	29.9	35.9	
ψ _{JT}	Junction-to-top characterization parameter	12.6	5.3	6.7	
ψ _{JB}	Junction-to-board characterization parameter	21.1	29.6	35.3	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, [SPRA953](#).

6.5 Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS		V _{CC}	T _A = 25°C			SN54HC594 ⁽¹⁾ –55°C to 125°C		SN74HC594 –40°C to 85°C		SN74HC594 –40°C to 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
V _{OH}	V _I = V _{IH} or V _{IL}	I _{OH} = –20 μA	2 V	1.9	1.998		1.9		1.9			V	
			4.5 V	4.4	4.499		4.4		4.4				
			6 V	5.9	5.999		5.9		5.9				
		4.5 V	Q _H [†] I _{OH} = –4 mA	3.98	4.3		3.7		3.84		3.84		
			Q _A – Q _H I _{OH} = –6 mA	3.98	4.3		3.7		3.84		3.84		
			Q _H [†] I _{OH} = –5.2 mA	5.48	5.8		5.2		5.34		5.34		
Q _A – Q _H I _{OH} = –7.8 mA	5.48	5.8			5.2		5.34		5.34				
V _{OL}	V _I = V _{IH} or V _{IL}	I _{OL} = 20 μA	2 V		0.002	0.1			0.1		0.1	V	
			4.5 V		0.001	0.1			0.1		0.1		
			6 V		0.001	0.1			0.1		0.1		
		4.5 V	Q _H [†] I _{OL} = 4 mA		0.17	0.26			0.4		0.33		0.33
			Q _A – Q _H I _{OL} = 6 mA		0.17	0.26			0.4		0.33		0.33
			Q _H [†] I _{OL} = 5.2 mA		0.15	0.26			0.4		0.33		0.33
Q _A – Q _H I _{OL} = 7.8 mA		0.15		0.26			0.4		0.33	0.33			
I _I	V _I = V _{CC} or 0	6 V		±0.1	±100		±1000		±1000		±1000	nA	
I _{CC}	V _I = V _{CC} or 0, I _O = 0	6 V			8		160		80		80	μA	
C _i		2 V to 6 V			3	10		10		10			pF

(1) Product Preview

6.6 Switching Characteristics: $C_L = 50 \text{ pF}$

 over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC594 ⁽¹⁾ –55°C to 125°C		SN74HC594 –40°C to 85°C		SN74HC594 –40°C to 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f_{max}			2 V	5	8		3.3		4		4	MHz	
			4.5 V	25	35		17		20		20		
			6 V	29	40		20		24		24		
t_{pd}	SRCLK	Q_H	2 V		50	150		225		185		200	ns
			4.5 V		20	30		45		37		42	
			6 V		15	25		38		31		36	
	RCLK	$Q_A - Q_H$	2 V		50	150		225		185		200	
			4.5 V		20	30		45		37		42	
			6 V		15	25		38		31		36	
t_{PHL}	$\overline{\text{SRCLR}}$	Q_H	2 V		50	150		225		185		200	ns
			4.5 V		20	30		45		37		42	
			6 V		15	25		38		31		36	
	$\overline{\text{RCLR}}$	$Q_A - Q_H$	2 V		50	125		185		155		170	
			4.5 V		20	25		37		31		36	
			6 V		15	21		31		26		31	
t_t		Q_H	2 V		38	75		110		95		110	ns
			4.5 V		8	15		22		19		21	
			6 V		6	13		19		16		18	
		$Q_A - Q_H$	2 V		38	60		90		75		85	
			4.5 V		8	12		18		15		17	
			6 V		6	10		15		13		15	

(1) Product Preview

6.7 Switching Characteristics: $C_L = 150 \text{ pF}$

 over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 4](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC}	$T_A = 25^\circ\text{C}$			SN54HC594 ⁽¹⁾ –55°C to 125°C		SN74HC594 –40°C to 85°C		SN74HC594 –40°C to 125°C		UNIT
				MIN	TYP	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t_{pd}	RCLK	$Q_A - Q_H$	2 V		90	200		300		250		270	ns
			4.5 V		23	40		60		50		55	
			6 V		19	34		51		43		48	
t_{PHL}	$\overline{\text{RCLR}}$	$Q_A - Q_H$	2 V		90	200		300		250		270	ns
			4.5 V		23	40		60		50		55	
			6 V		19	34		51		43		48	
t_t		$Q_A - Q_H$	2 V		45	210		315		265		285	ns
			4.5 V		17	42		63		53		58	
			6 V		13	36		53		45		50	

(1) Product Preview

6.8 Timing Requirements

over recommended operating free-air temperature range (unless otherwise noted)

		V _{CC}	T _A = 25°C		SN54HC594 ⁽¹⁾ –55°C to 125°C		SN74HC594 –40°C to 85°C		SN74HC594 –40°C to 125°C		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f _{clock}	Clock frequency	2 V	5		3.3		4		4		MHz
		4.5 V	25		17		20		20		
		6 V	29		20		24		24		
t _w	SRCLK or RCLK high or low	2 V	100	150	125	130	ns				
		4.5 V	20	30	25	27					
		6 V	17	25	21	23					
	SRCLR or RCLR low	2 V	100	150	125	130					
		4.5 V	20	30	25	27					
		6 V	17	25	21	23					
t _{su}	SER before SRCLK↑	2 V	90	135	110	115	ns				
		4.5 V	18	27	22	24					
		6 V	15	23	19	21					
	SRCLK↑ before RCLK↑ ⁽²⁾	2 V	90	135	110	115					
		4.5 V	18	27	22	24					
		6 V	15	23	19	21					
	SRCLR low before RCLK↑	2 V	50	75	63	68	ns				
		4.5 V	10	15	13	15					
		6 V	9	13	11	13					
		SRCLR high (inactive) before SRCLK↑	2 V	20	20	20		20			
			4.5 V	10	10	10		10			
			6 V	10	10	10		10			
RCLR high (inactive) before SRCLK↑	2 V	5	5	5	5						
	4.5 V	5	5	5	5						
	6 V	5	5	5	5						
t _h	Hold time, SER after SRCLK↑	2 V	5	5	5	5	ns				
		4.5 V	5	5	5	5					
		6 V	5	5	5	5					

(1) Product Preview

(2) This setup time ensures that the output register receives stable data from the shift-register outputs. The clocks may be tied together, in which case the output register is one clock pulse behind the shift register.

6.9 Operating Characteristics

T_A = 25°C

PARAMETER	TEST CONDITIONS	TYP	UNIT
C _{pd} Power dissipation capacitance	No load	395	pF

SN54HC594, SN74HC594

SCLS040G – DECEMBER 1982 – REVISED MARCH 2015

www.ti.com

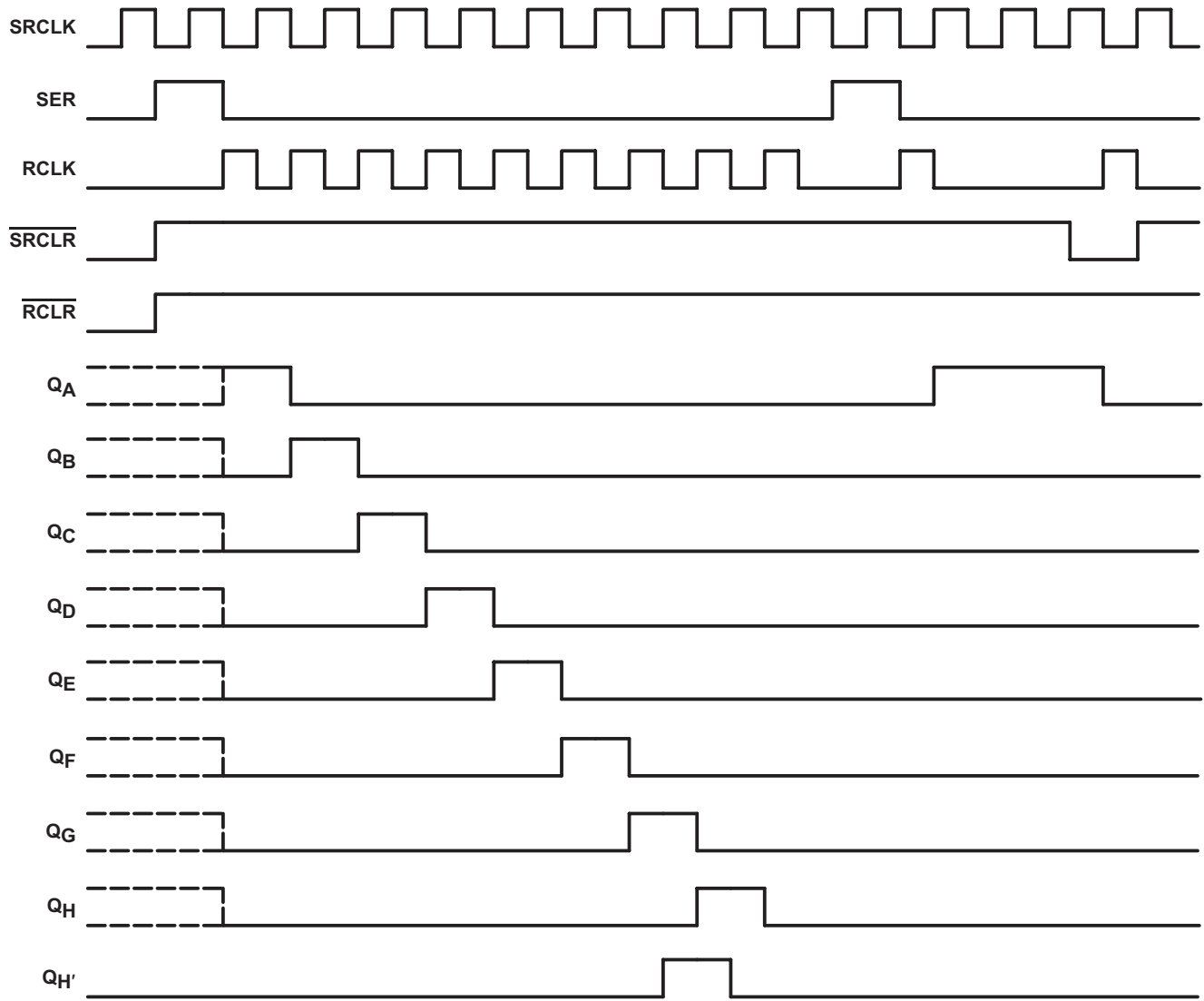
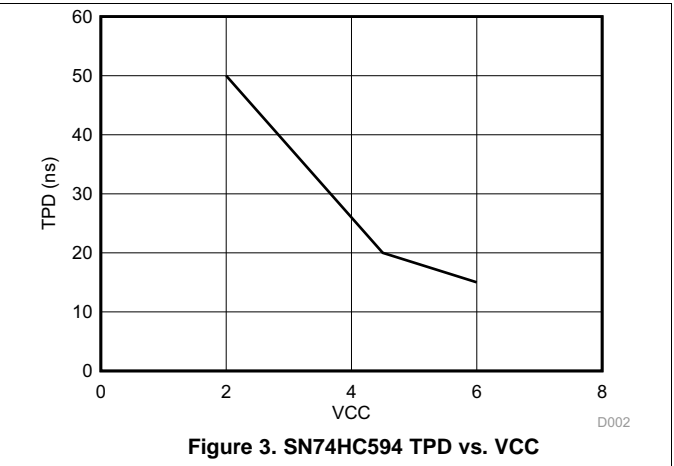
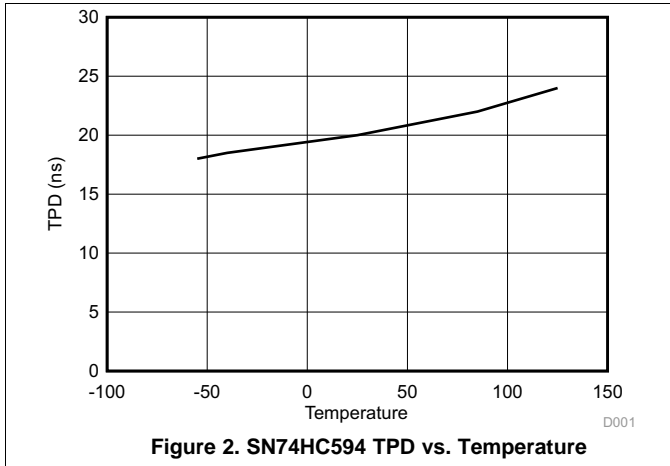


Figure 1. Timing Diagram

6.10 Typical Characteristics



7 Parameter Measurement Information

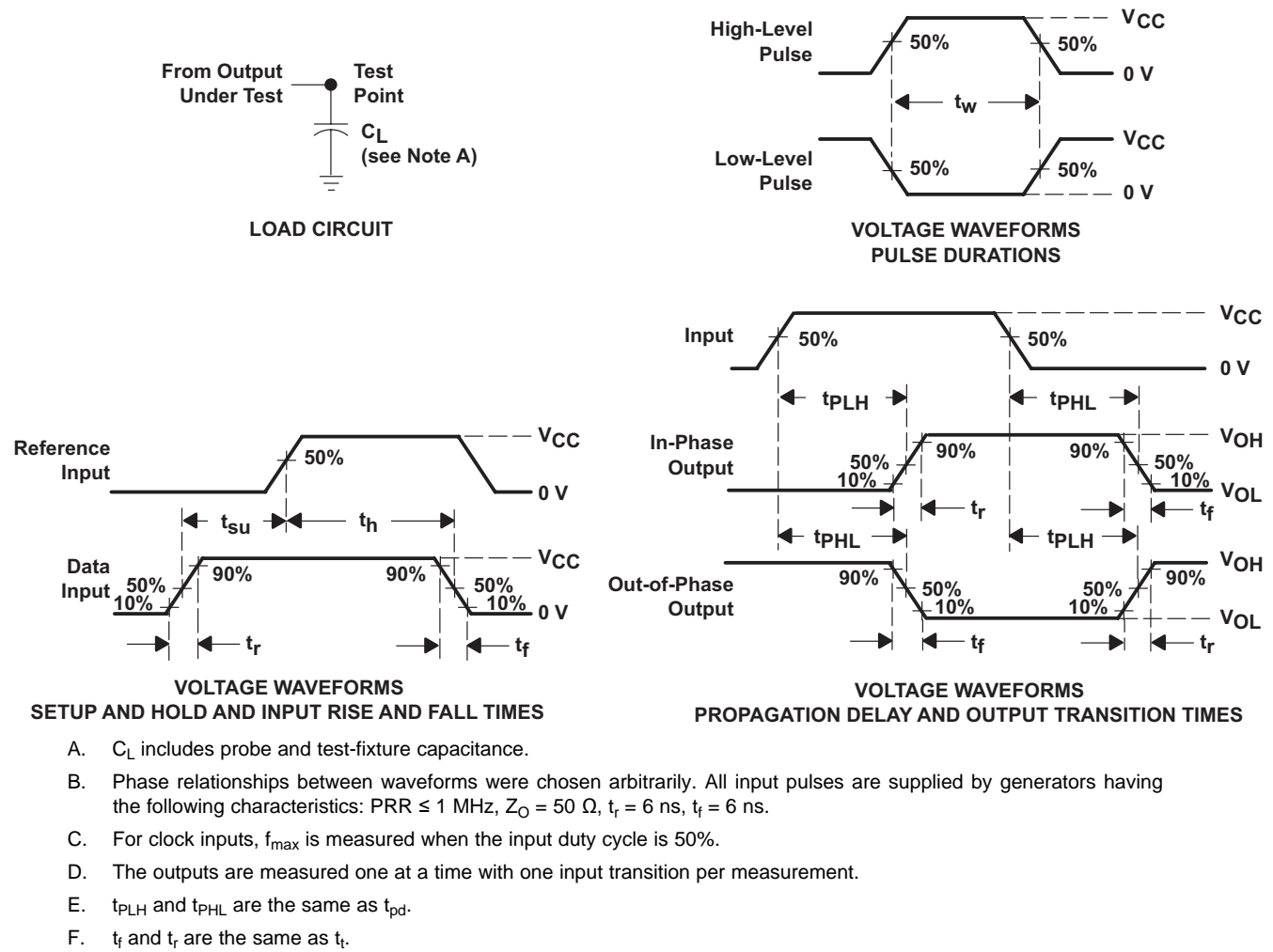


Figure 4. Load Circuit and Voltage Waveforms

8 Detailed Description

8.1 Overview

The SNx4HC594 devices contain an 8-bit serial-in, parallel-out shift register that feeds an 8-bit D-type storage register. Separate clocks and direct overriding clear (\overline{RCLR} , \overline{SRCLR}) inputs are provided on both the shift and storage registers. A serial (Q_H) output is provided for cascading purposes.

Both the shift register (SRCLK) and storage register (RCLK) clocks are positive edge triggered. If both clocks are connected together, the shift register always is one count pulse ahead of the storage register.

The parallel ($Q_A - Q_H$) outputs have high-current capability. Q_H is a standard output.

8.2 Functional Block Diagram

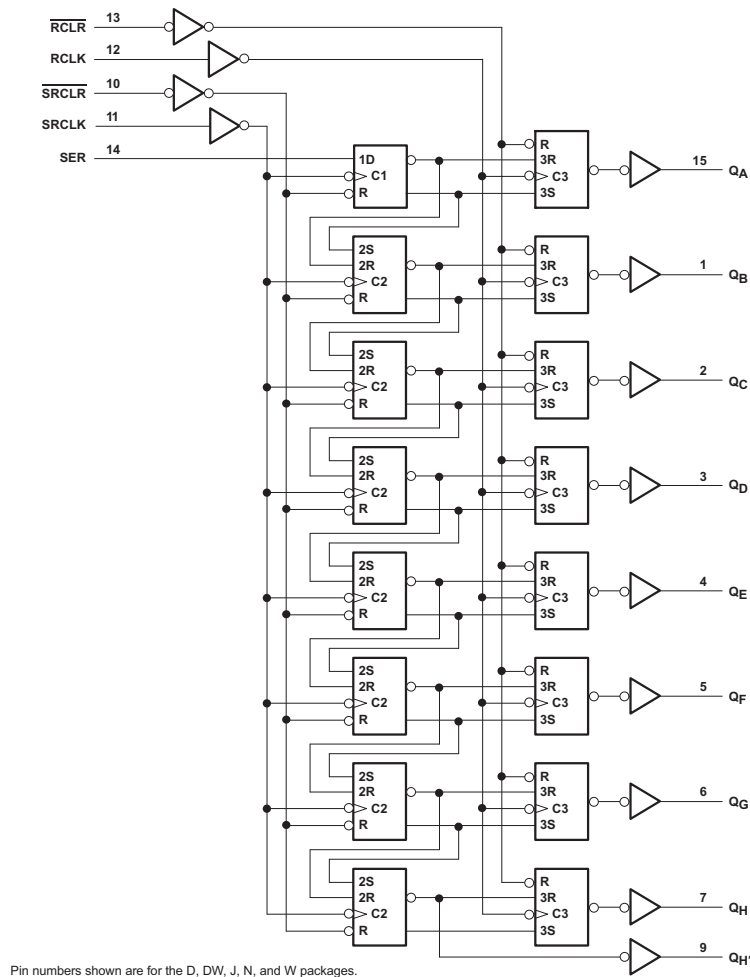


Figure 5. Logic Diagram (Positive Logic)

8.3 Feature Description

The wide operating range allows the device to be used in a variety of systems that use different logic levels. The high-current outputs allow the device to drive medium loads without significant drops in output voltage. In addition, the low power consumption makes this device a good choice for portable and battery power-sensitive applications.

8.4 Device Functional Modes

Table 1. Function Table

INPUTS					FUNCTION
SER	SRCLK	SRCLR	RCLK	RCLR	
X	X	L	X	X	Shift register is cleared.
L	↑	H	X	X	First stage of shift register goes low. Other stages store the data of previous stage, respectively.
H	↑	H	X	X	First stage of shift register goes high. Other stages store the data of previous stage, respectively.
L	↓	H	X	X	Shift register state is not changed.
X	X	X	X	L	Storage register is cleared.
X	X	X	↑	H	Shift register data is stored in the storage register.
X	X	X	↓	H	Storage register state is not changed.

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

The SN74HC594 is a low drive CMOS device that can be used for a multitude of bus interface type applications where output ringing is a concern. The low drive and slow edge rates will minimize overshoot and undershoot on the outputs.

9.2 Typical Application

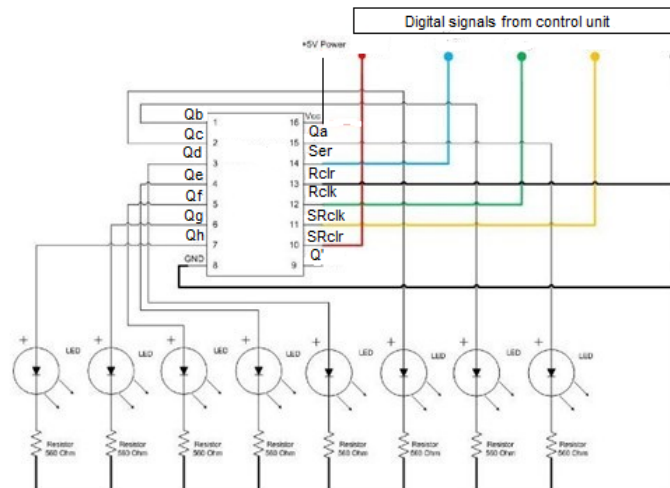


Figure 6. Typical Application Schematic

9.2.1 Design Requirements

This device uses CMOS technology and has balanced output drive. Take care to avoid bus contention because it can drive currents that would exceed maximum limits. The high drive will also create fast edges into light loads so consider routing and load conditions to prevent ringing.

Typical Application (continued)

9.2.2 Detailed Design Procedure

- Recommended input conditions:
 - Rise time and fall time specs see $(\Delta t/\Delta V)$ in *Recommended Operating Conditions* table.
 - Specified High and low levels. See V_{IH} and V_{IL} in *Recommended Operating Conditions* table.
 - Inputs are overvoltage tolerant allowing them to go as high as 5.5 V at any valid V_{CC}
- Recommended output conditions:
 - Load currents should not exceed 35 mA per output and 70 mA total for the part
 - Outputs should not be pulled above V_{CC}

9.2.3 Application Curves

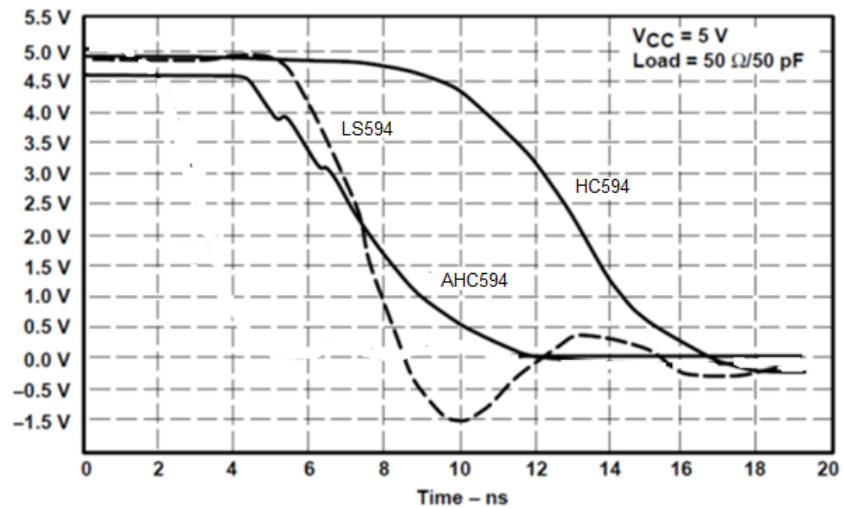


Figure 7. Switching Characteristics Comparison

10 Power Supply Recommendations

The power supply can be any voltage between the minimum and maximum supply voltage rating located in the [Recommended Operating Conditions](#).

Each V_{CC} terminal should have a good bypass capacitor to prevent power disturbance. For devices with a single supply, TI recommends a 0.1- μF capacitor and if there are multiple V_{CC} terminals then TI recommends a 0.01- μF or 0.022- μF capacitor for each power terminal. Multiple bypass capacitors can be paralleled to reject different frequencies of noise. Frequencies of 0.1 μF and 1 μF are commonly used in parallel. The bypass capacitor should be installed as close as possible to the power terminal for best results.

11 Layout

11.1 Layout Guidelines

When using multiple bit logic devices inputs should not ever float.

In many cases, functions or parts of functions of digital logic devices are unused, for example, when only two inputs of a triple-input AND gate are used or only three of the four buffer gates are used. Such input pins should not be left unconnected because the undefined voltages at the outside connections result in undefined operational states. Specified below are the rules that must be observed under all circumstances. All unused inputs of digital logic devices must be connected to a high or low bias to prevent them from floating. The logic level that should be applied to any particular unused input depends on the function of the device. Generally they will be tied to GND or V_{CC} whichever make more sense or is more convenient. Floating outputs is generally acceptable, unless the part is a transceiver. If the transceiver has an output enable pin it will disable the outputs section of the part when asserted. This will not disable the input section of the I.O's so they also cannot float when disabled.

11.2 Layout Example

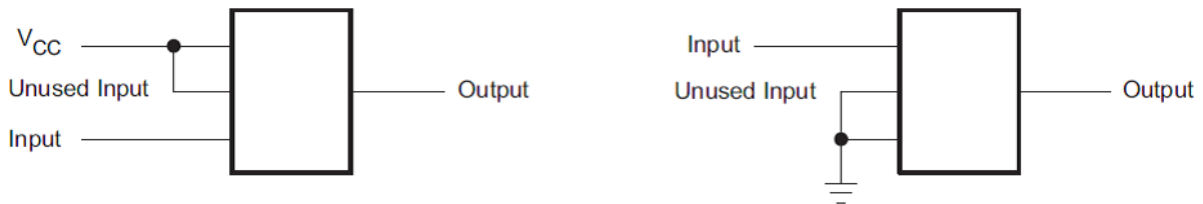


Figure 8. Layout Recommendation

12 Device and Documentation Support

12.1 Documentation Support

12.1.1 Related Documentation

For related documentation see the following:

Implications of Slow or Floating CMOS Inputs, [SCBA004](#)

12.2 Trademarks

All trademarks are the property of their respective owners.

12.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

12.4 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74HC594D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC594	Samples
SN74HC594DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC594	Samples
SN74HC594DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC594	Samples
SN74HC594DT	ACTIVE	SOIC	D	16	250	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC594	Samples
SN74HC594DW	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC594	Samples
SN74HC594DWE4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC594	Samples
SN74HC594DWG4	ACTIVE	SOIC	DW	16	40	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC594	Samples
SN74HC594DWR	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC594	Samples
SN74HC594DWRE4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC594	Samples
SN74HC594DWRG4	ACTIVE	SOIC	DW	16	2000	Green (RoHS & no Sb/Br)	NIPDAU	Level-1-260C-UNLIM	-40 to 125	HC594	Samples
SN74HC594N	ACTIVE	PDIP	N	16	25	Green (RoHS & no Sb/Br)	NIPDAU	N / A for Pkg Type	-40 to 125	SN74HC594N	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

- (3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

Important Information and Disclaimer:The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74HC594DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN74HC594DWR	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1
SN74HC594DWRG4	SOIC	DW	16	2000	330.0	16.4	10.75	10.7	2.7	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74HC594DR	SOIC	D	16	2500	333.2	345.9	28.6
SN74HC594DWR	SOIC	DW	16	2000	350.0	350.0	43.0
SN74HC594DWRG4	SOIC	DW	16	2000	350.0	350.0	43.0

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AC.

D (R-PDSO-G16)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

GENERIC PACKAGE VIEW

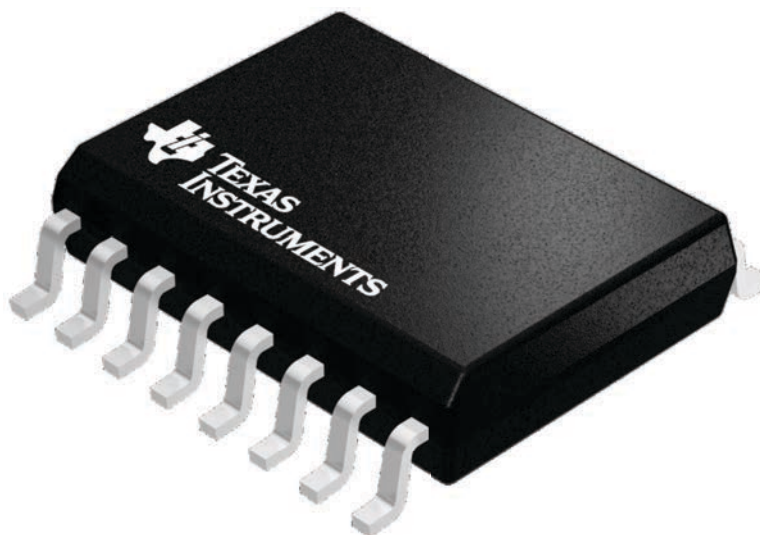
DW 16

SOIC - 2.65 mm max height

7.5 x 10.3, 1.27 mm pitch

SMALL OUTLINE INTEGRATED CIRCUIT

This image is a representation of the package family, actual package may vary.
Refer to the product data sheet for package details.



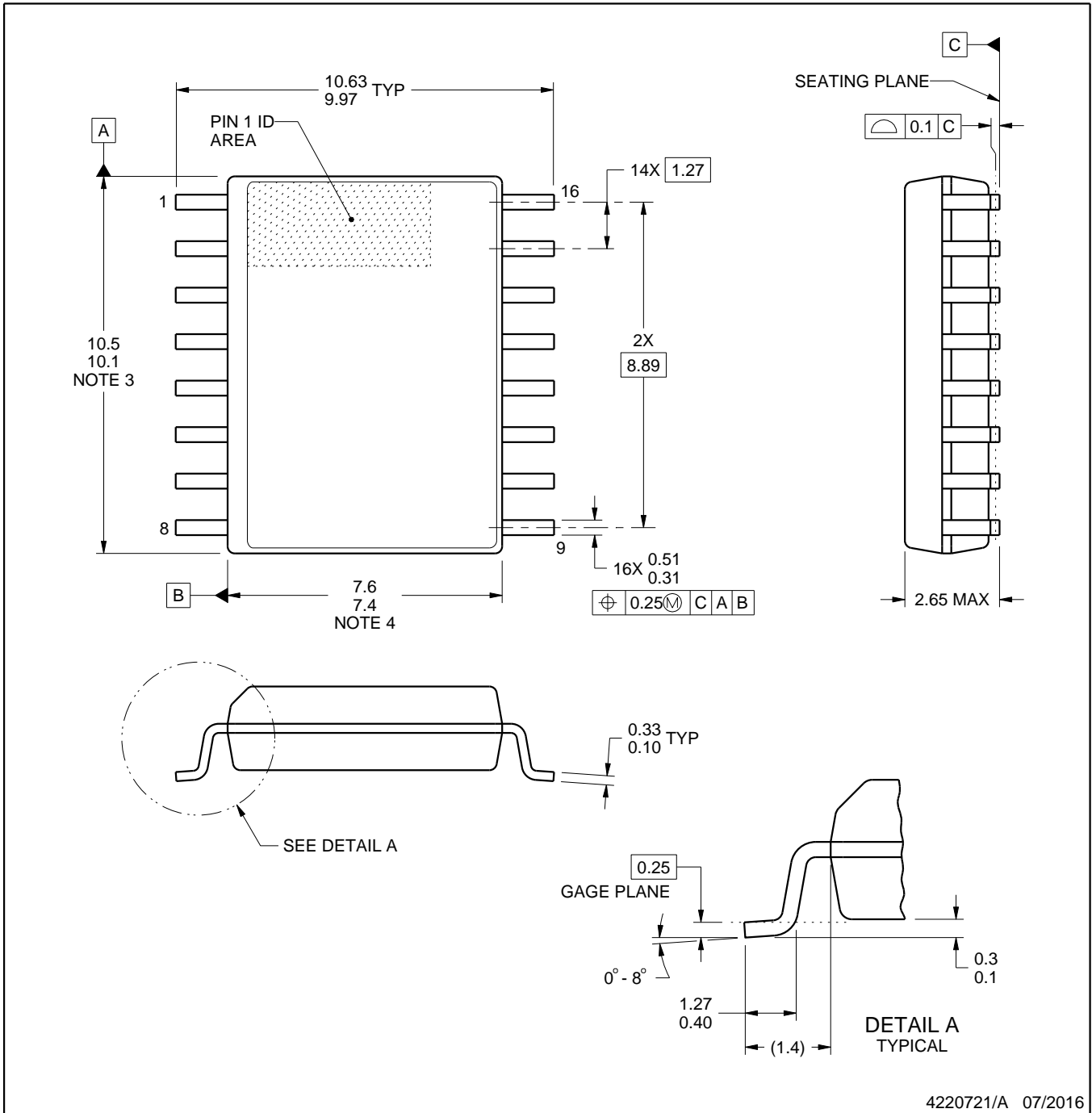
4224780/A



DW0016A

PACKAGE OUTLINE SOIC - 2.65 mm max height

SOIC



4220721/A 07/2016

NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm, per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm, per side.
5. Reference JEDEC registration MS-013.

EXAMPLE BOARD LAYOUT

DW0016A

SOIC - 2.65 mm max height

SOIC



LAND PATTERN EXAMPLE
SCALE:7X



SOLDER MASK DETAILS

4220721/A 07/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

DW0016A

SOIC - 2.65 mm max height

SOIC



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:7X

4220721/A 07/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (www.ti.com/legal/termsofsale.html) or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
Copyright © 2020, Texas Instruments Incorporated